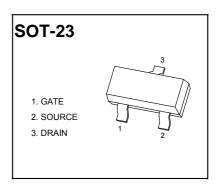


# **SOT-23 Plastic-Encapsulate MOSFETS**

#### 20V P-Channel MOSFET

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> Typ	I <sub>D</sub> Max
-20V	70mΩ@4.5V	-3.0A
	78mΩ@3.3V	0.071



#### **Features**

Trench FET Power MOSFET

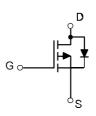
#### **MARKING**



#### **APPLICATION**

- Load Switch for Portable Devices
- DC/DC Converter

#### **Equivalent circuit**



#### **PACKAGE SPECIFICATIONS**

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (pcs)	Box Size (mm)	QTY/Box (pcs)	Carton Size (mm)	Q'TY/Carton (pcs)
SOT-23	7'	330	3000	203×203×195	45000	438×438×220	180000

#### Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	-20	V	
Gate-Source Voltage		$V_{GS}$	±10	V
Outlineau Brain Outline	T <sub>A</sub> = 25 °C	lь	-3.0	Α
Continuous Drain Current	T <sub>A</sub> = 70°C		-2.5	
Pulsed Drain Current 1)		I <sub>DM</sub>	-12	Α
Maximum Power Dissipation 2)	$T_A = 25 ^{\circ}\text{C}$ $T_1 = 70 ^{\circ}\text{C}$	P <sub>D</sub>	1.2	W
	$T_A = 70^{\circ}C$		0.9	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-50 to 150	°C
Junction-to-Ambient Thermal Resistance (PCB mounted) <sup>2)</sup>		R <sub>thJA</sub>	100	°C/W

The above data are for reference only.

Notes
1) Pulse width limited by maximum junction temperature.

<sup>2)</sup> Surface Mounted on FR4 Board,  $t \le 5$  sec.



#### MOSFET ELECTRICAL CHARACTERISTICS

## $T_a=25$ °C unless otherwise specified

Parameter	Symbol	Test Condition	Min	Тур	Max	Units	
Static							
Drain-source breakdown voltage	V(BR)DSS	V <sub>GS</sub> = 0V, I <sub>D</sub> =-250µA	-20			V	
Gate-source threshold voltage	V <sub>G</sub> S(th)	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.4	-0.6	-1		
Gate-source leakage	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±10V			±100	nA	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V			-1	μΑ	
Drain agurag an atata ragistanga <sup>a</sup>	_	V <sub>G</sub> S =-4.5V, I <sub>D</sub> =-3A		70	90	0	
Drain-source on-state resistance <sup>a</sup>	RDS(on)	V <sub>GS</sub> =-3.3V, I <sub>D</sub> =-2.0A		78	100	mΩ	
Forward transconductance <sup>a</sup>	<b>g</b> fs	V <sub>DS</sub> =-5V, I <sub>D</sub> =-2.8A		4.0		S	
Dynamic <sup>b</sup>			•				
Input capacitance	C <sub>iss</sub>			330		pF	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> =-10V,V <sub>GS</sub> =0V,f =1MHz		50			
Reverse transfer capacitance	C <sub>rss</sub>			45			
	0	V <sub>DS</sub> =-10V,V <sub>GS</sub> =-4.5V,I <sub>D</sub> =-3A		6.6			
Total gate charge	Qg			0.8		nC	
Gate-source charge	Q <sub>gs</sub>	V <sub>DS</sub> =-10V,V <sub>GS</sub> =-4.5V,I <sub>D</sub> =-3A		0.7		nC	
Gate-drain charge	$Q_{gd}$			1.4			
Turn-on delay time	td(on)	V 40V D 400		11			
Rise time	tr	$V_{DD}$ =-10V, $R_L$ =10 $\Omega$ ,		12		ns	
Turn-off delay time	td(off)	V <sub>GEN</sub> =-4.5V,Rg=3.3Ω		18			
Fall time	tf	- VGLIVOV,119-0.032		30			
Drain-source body diode characteristics							
Continuous source-drain diode current	Is	T <sub>C</sub> =25℃			-1.5	Α	
Body diode voltage	$V_{SD}$	Is=-2A		-0.85	-1.2	V	

a) Pulse test: pulse width ≤ 300us, duty cycle≤ 2%

b) Guaranteed by design, not subject to production testing



#### **Typical Characteristics**

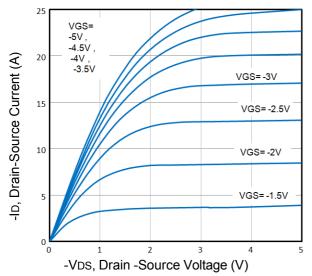


Fig1. Typical Output Characteristics

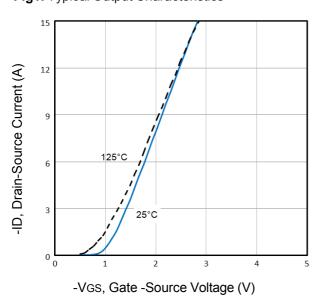


Fig3. Typical Transfer Characteristics

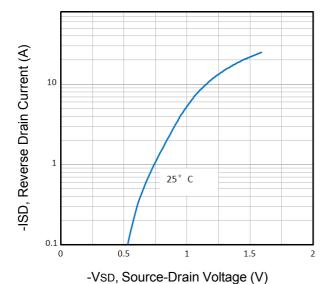


Fig5. Typical Source-Drain Diode Forward Voltage

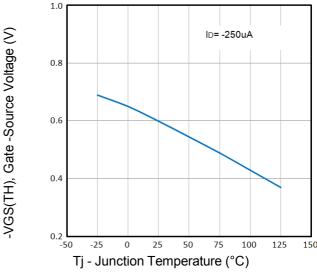


Fig2. Normalized Threshold Voltage Vs. Temperature

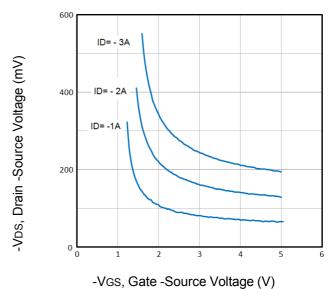
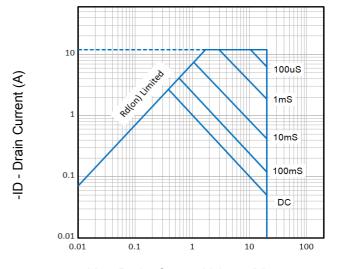


Fig4. Drain -Source Voltage vs Gate -Source Voltage



-VDS, Drain -Source Voltage (V)

Fig6. Maximum Safe Operating Area

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#### **Typical Characteristics**

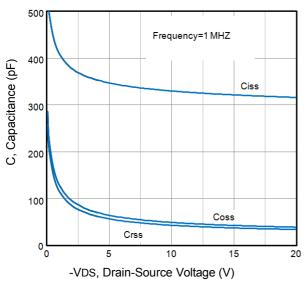


Fig7. Typical Capacitance Vs. Drain-Source Voltage

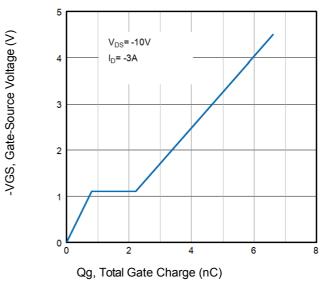


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

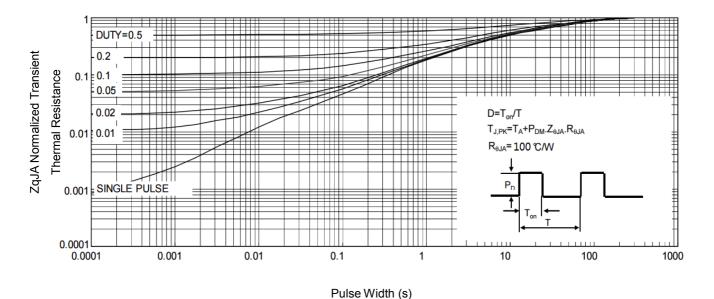


Fig9. Normalized Maximum Transient Thermal Impedance

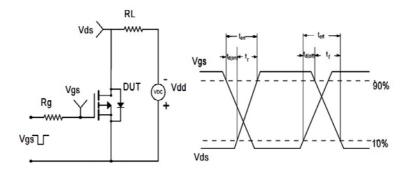


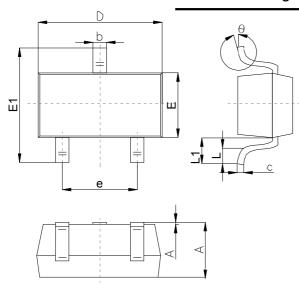
Fig10. Switching Time Test Circuit and waveforms

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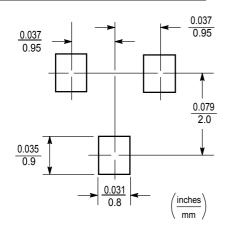
### **Outlitne Drawing**

#### SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters				
	Min	Тур	Max		
Α	1.00		1.40		
A1			0.10		
b	0.35		0.50		
С	0.10		0.20		
D	2.70	2.90	3.10		
Е	1.40		1.60		
E1	2.4		2.80		
е		1.90			
L	0.10		0.30		
L1	0.4				
θ	0°		10°		

### **Suggested Pad Layout**



#### Note:

Controlling

dimension:in/millimeters. 2.General

tolerance: ±0.05mm.

3. The pad layout is for reference purposes only.

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